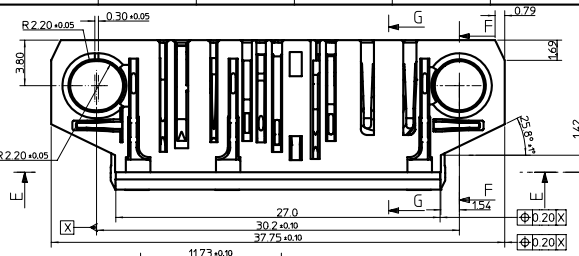
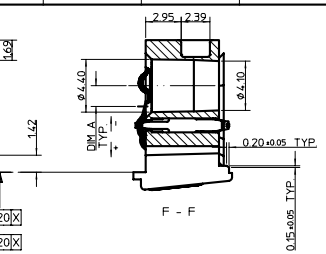
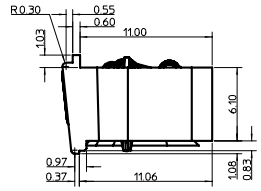
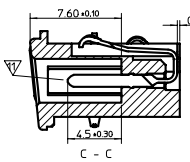
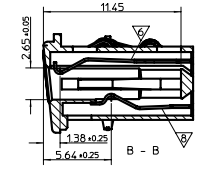
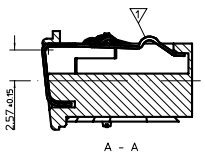


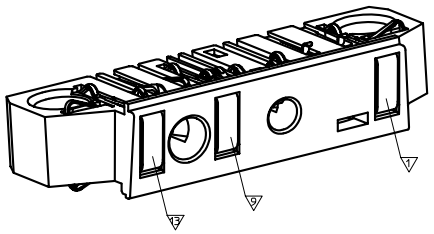


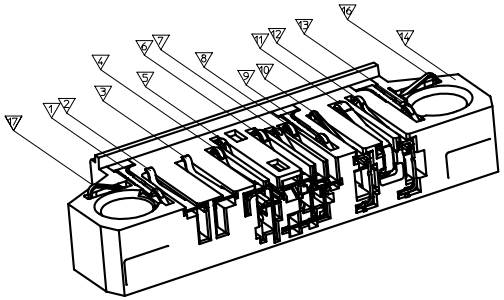


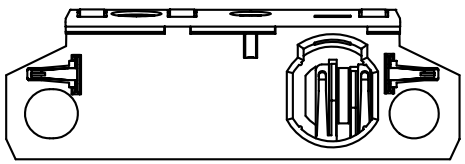




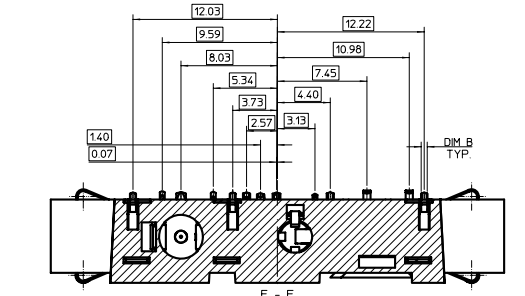


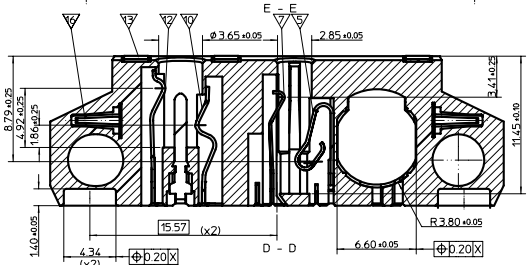




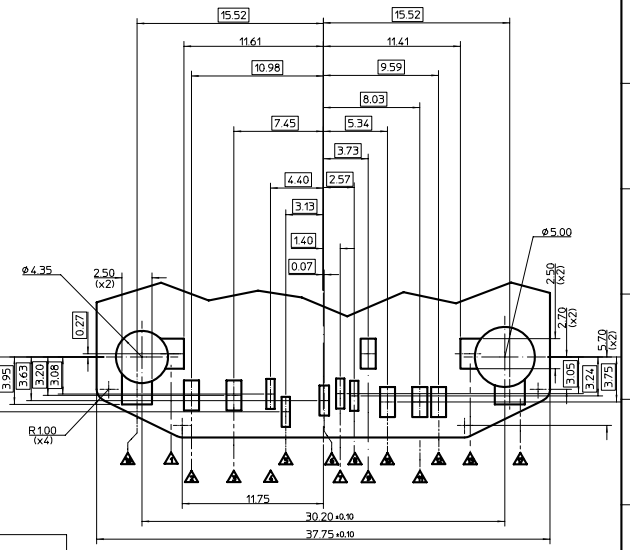


OPTION 2 : PART No. 91304-0003



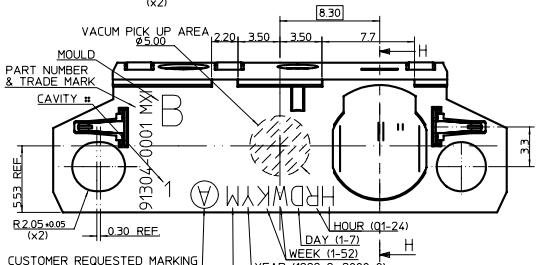


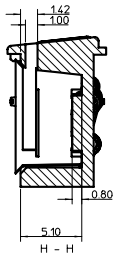
	DIM A	DIM B	POSITION	PCB BEAM HEIGHT	COMPONENT	COMPONENT MATERIALS AND PLATING
7	-0.27 ±0.25	0.50 ±0.05	⊕ø0.30 X	0.5 +0.30 -0.10	CHARGER PAD NEGATIVE	MATERIAL: 0.22mm REF THICK COPPER ALLOY (C7025) PLATING: CONTACT: 0.10um GOLD FLASH OVER 1.0um PdNi OVER 1.27um Ni PCB TAIL: 0.20um GOLD OVER 1.27um Ni
9	-0.27 ±0.25	0.50 ±0.05	⊕ø0.30 X		CHARGER PAD CONTROL	
13	-0.27 ±0.25	0.50 ±0.05	⊕ø0.30 X		CHARGER PAD POSITIVE	
2	3.20 ±0.25	0.60 ±0.05	⊕ø0.30 X	1.05 +0.30 -0.20	IMICN MICROPHONE TERMINAL	MATERIAL: 0.15mm REF THICK BERYLLIUM COPPER PLATING: CONTACT: 0.20um GOLD FLASH OVER 1.27um Ni PCB TAIL: 0.20um GOLD FLASH OVER 1.27um Ni
3	3.20 ±0.25	0.60 ±0.05	⊕ø0.30 X		IMICP MICROPHONE TERMINAL	
10	3.72 ±0.25	0.40 ±0.05	⊕ø0.30 X	0.5 +0.30 -0.10	DC NEGATIVE TERMINAL	MATERIAL: 0.25mm REF THICK BERYLLIUM COPPER PLATING: CONTACT: 0.10um GOLD FLASH OVER 1.0um PdNi OVER 1.27um Ni UNDERCOAT PCB TAIL: 0.10um GOLD FLASH OVER 0.2-1.0um PdNi OVER 1.27um Ni UNDERCOAT
12	3.71 ±0.25	0.40 ±0.05	⊕ø0.30 X		DC CONTROL TERMINAL	
11	3.78 ±0.25	0.80 ±0.05	⊕ø0.30 X	0.5 +0.30 -0.10	DC-PIN POSITIVE TERMINAL	MATERIAL: 1.0mm REF THICK COPPER ALLOY WIRE PLATING: CONTACT: 3um Ni ON 1.27um Ni UNDERCOAT PCB TAIL: 0.2um GOLD OVER 1.27um Ni UNDERCOAT
4	3.09 ±0.25	0.60 ±0.05	⊕ø0.30 X	0.5 +0.30 -0.10	INT CONTACT	MATERIAL: 0.20mm REF THICK COPPER ALLOY (C7025) 4 6 7
5	4.57 ±0.25	0.40 ±0.05	⊕ø0.30 X		XEARP	MATERIAL: 0.25mm REF THICK BERYLLIUM COPPER 5
6	3.63 ±0.25	0.65 ±0.05	⊕ø0.30 X		XMICN	MATERIAL: 0.20mm REF THICK PHOSPHOR BRONZE 8 PLATING: (ALL CONTACTS) CONTACT: 0.10um GOLD FLASH OVER 1.0um PdNi OVER 1.27um Ni PCB TAIL: 0.10um GOLD FLASH OVER 0.20-1.0um PdNi OVER 1.27um Ni
7	3.05 ±0.25	0.60 ±0.05	⊕ø0.30 X		XEARN	
8	3.20 ±0.25	0.60 ±0.05	⊕ø0.30 X		XMICP	
14					HOUSING	MATERIAL: POLYAMIDE 46, 45% GLASS FILL UL94 V-0, COLOUR BLACK
15	3.30 ±0.25			0.85 ±0.15 ON PCB SIDE	GROUNDING CONTACT	MATERIAL: 0.15mm REF THICK COPPER ALLOY (C7025) PLATING: CONTACT: 0.2um GOLD OVER 1.27um Ni PCB TAIL 0.2um GOLD OVER 1.27um MIN Ni
17	3.30 ±0.25			0.85 +0.20 -0.15 OPPSITE SIDE TO PCB	GROUNDING CONTACT	



RECOMMENDED PCB LAYOUT

PCB PAD LAYOUT - 0.30um GOLD OVER NICKEL





ITEM	PCB PAD AREA
2 3 9 10 12 11	2.50 x 1.25
4 5 7 8	2.50 x 0.90
1 13 14 15 17	SEE PCB LAYOUT
6	2.50 x 1.00

NOTE:

1: DATECODE TO BE LASERMARKED WITH 1.6mm HEIGHT TEXT.

PART No.	DESCRIPTION
91304-0002	WITH MICROPHONE
91304-0003	WITH MOUSTACHE

REV	DESCRIPTION
L	PCB BEAM CHANGES EC NO. E2000-0922 DRAWN: PCURTIN 00.05.10 CHK: APPR:

QUALITY SYMBOLS: MAJOR ▼ CRITICAL ▽

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±	±
3 PLACES	±	±
2 PLACES	±0.10	±
1 PLACE	±0.20	±
ANGULAR: ± 1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 5:1 | DESIGN UNITS ☒ mm ☐ INCH | THIRD ANGLE PROJECTION | DIMENSIONS: ☐ mm INCH ☐ INCH mm ☒ mm ONLY | SHT | REV | REVISE ON CAD ONLY

DRAWN BY & DATE: pcurtin 2000/06/21

CHECKED BY & DATE: MGOONEY 2000/06/26

APPROVED BY & DATE: JHORGAN 2000/06/22

CAD FILENAME

TITLE: MOBILE PHONE I/O CONNECTOR

molex MOLEX INCORPORATED

MATERIAL NO. SEE CHART | DRAWING NO. SD-91304-003 | SHEET NO. 1 of 1

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SIZE D